

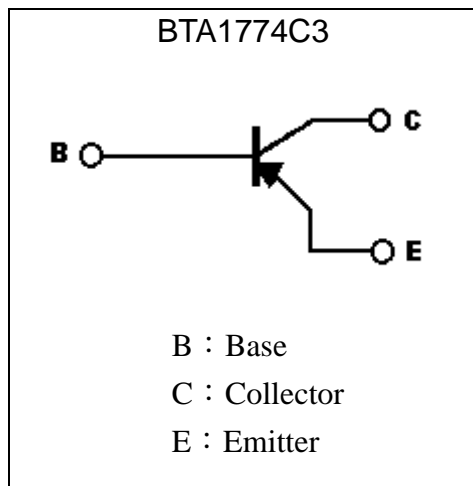
General Purpose PNP Epitaxial Planar Transistor

BTA1774C3

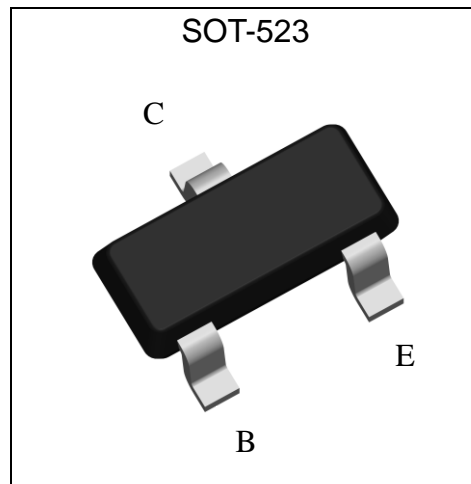
Description

- The BTA1774C3 is designed for use in driver stage of AF amplifier and general purpose amplification.
- High H_{FE} and excellent linearity
- Complementary to BTC4617C3.
- Pb-free lead plating and halogen-free package

Symbol

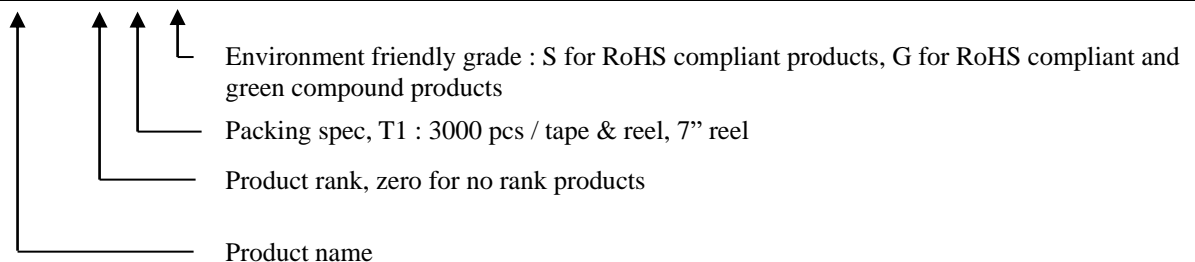


Outline



Ordering Information

Device	Package	Shipping
BTA1774C3-0-T1-G	SOT-523 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel





Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CB0}	-60	V
Collector-Emitter Voltage	V _{CEO}	-50	V
Emitter-Base Voltage	V _{EB0}	-6	V
Collector Current	I _C	-150	mA
Power Dissipation	P _d	150	mW
Thermal Resistance, Junction to Ambient	R _{θJA}	833.3	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

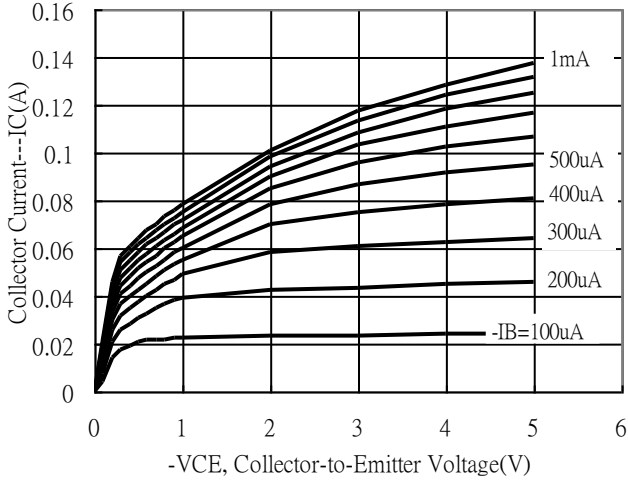
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	-60	-	-	V	I _C =-50μA
BV _{CEO}	-50	-	-	V	I _C =-1mA
BV _{EB0}	-6	-	-	V	I _E =-50μA
I _{CB0}	-	-	-0.1	μA	V _{CB} =-60V
I _{EB0}	-	-	-0.1	μA	V _{EB} =-6V
*V _{CE(sat)}	-	-	-0.5	V	I _C =-50mA, I _B =-5mA
h _{FE}	180	-	560	-	V _{CE} =-6V, I _C =-1mA
f _T	-	140	-	MHz	V _{CE} =-12V, I _C =-2mA, f=30MHz
C _{ob}	-	4	5	pF	V _{CB} =-12V, I _E =0, f=1MHz

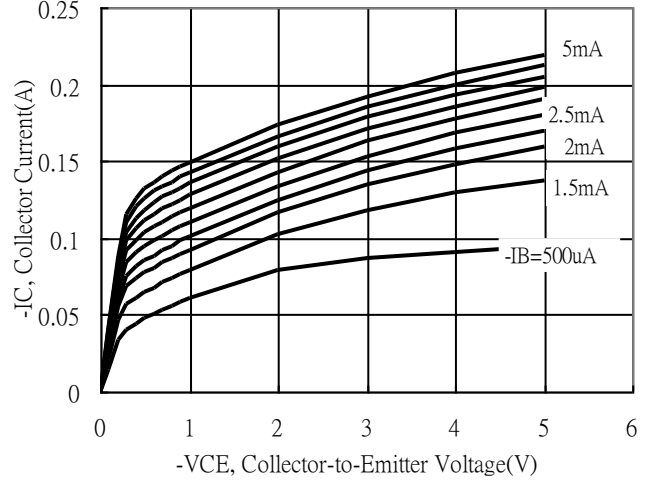
*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Typical Characteristics

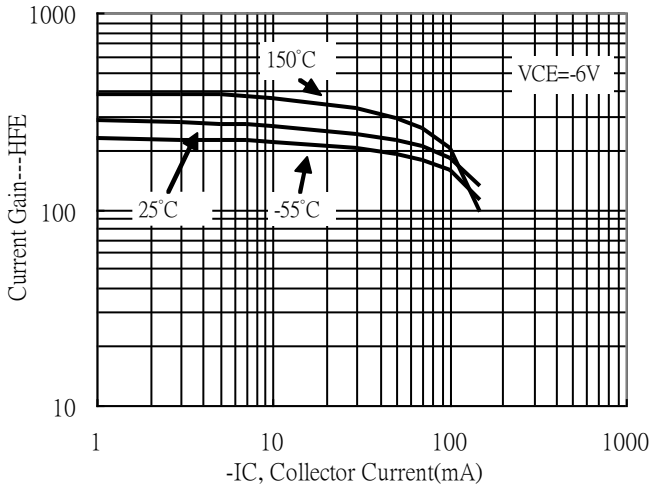
Emitter Grounded Output Characteristics



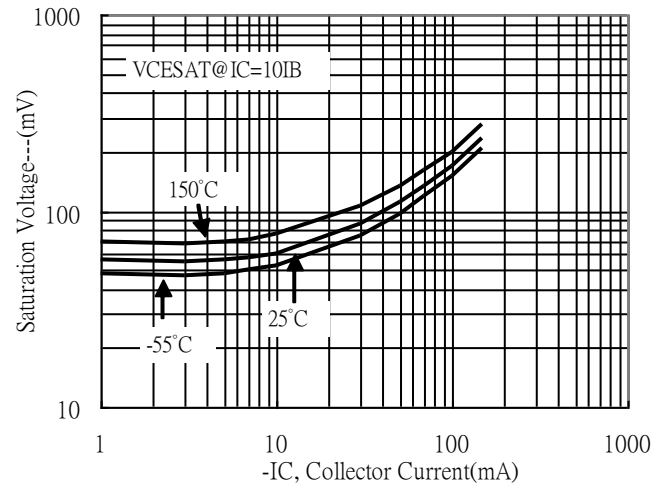
Emitter Grounded Output Characteristics



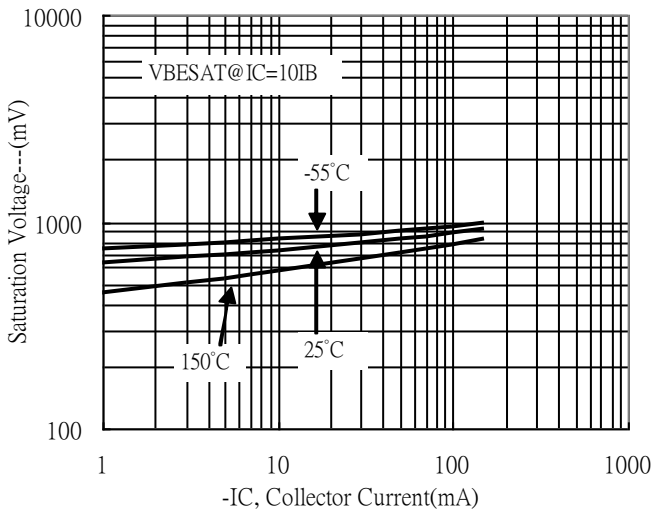
Current Gain vs Collector Current



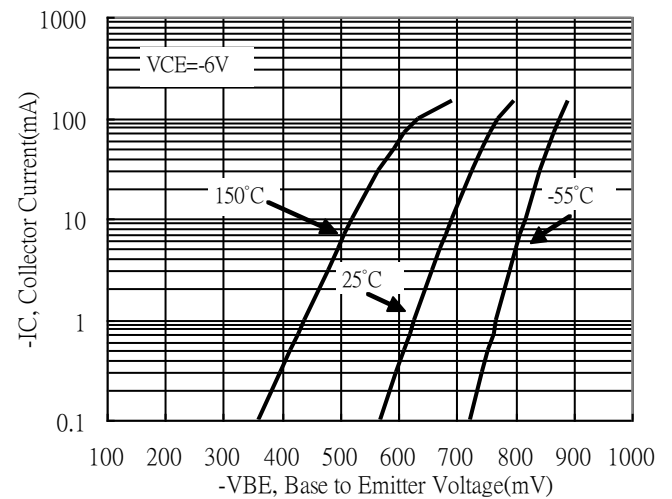
Saturation Voltage vs Collector Current



Saturation Voltage vs Collector Current

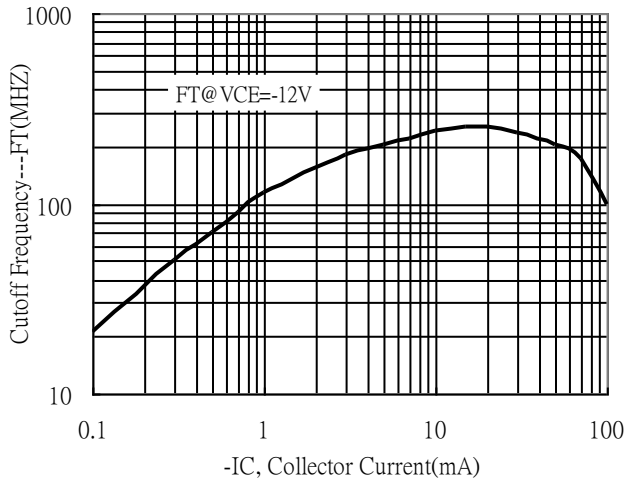


On Voltage vs Collector Current

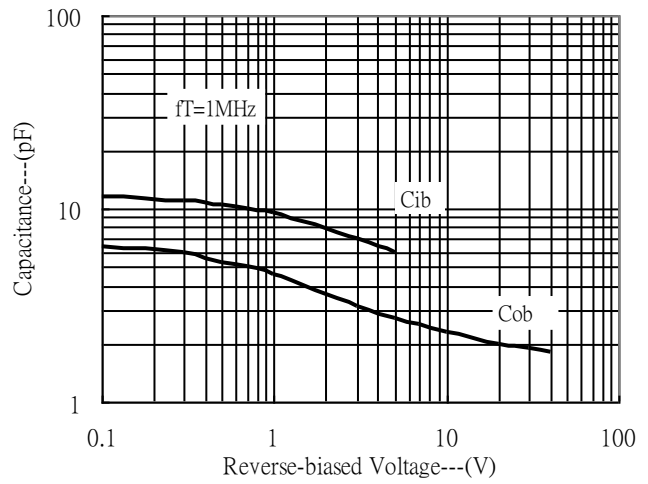


Typical Characteristics

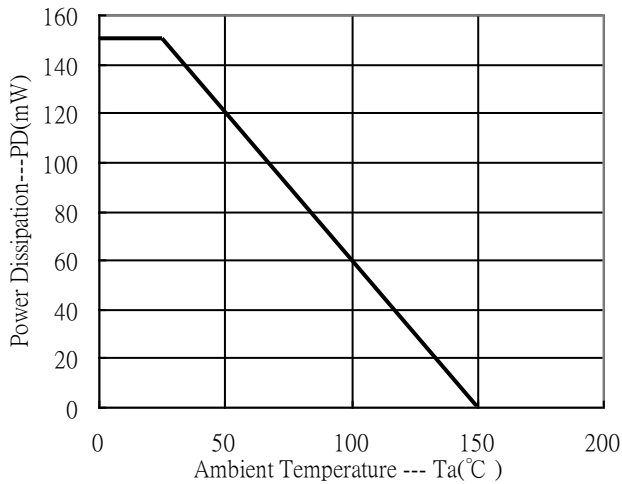
Cutoff Frequency vs Collector Current



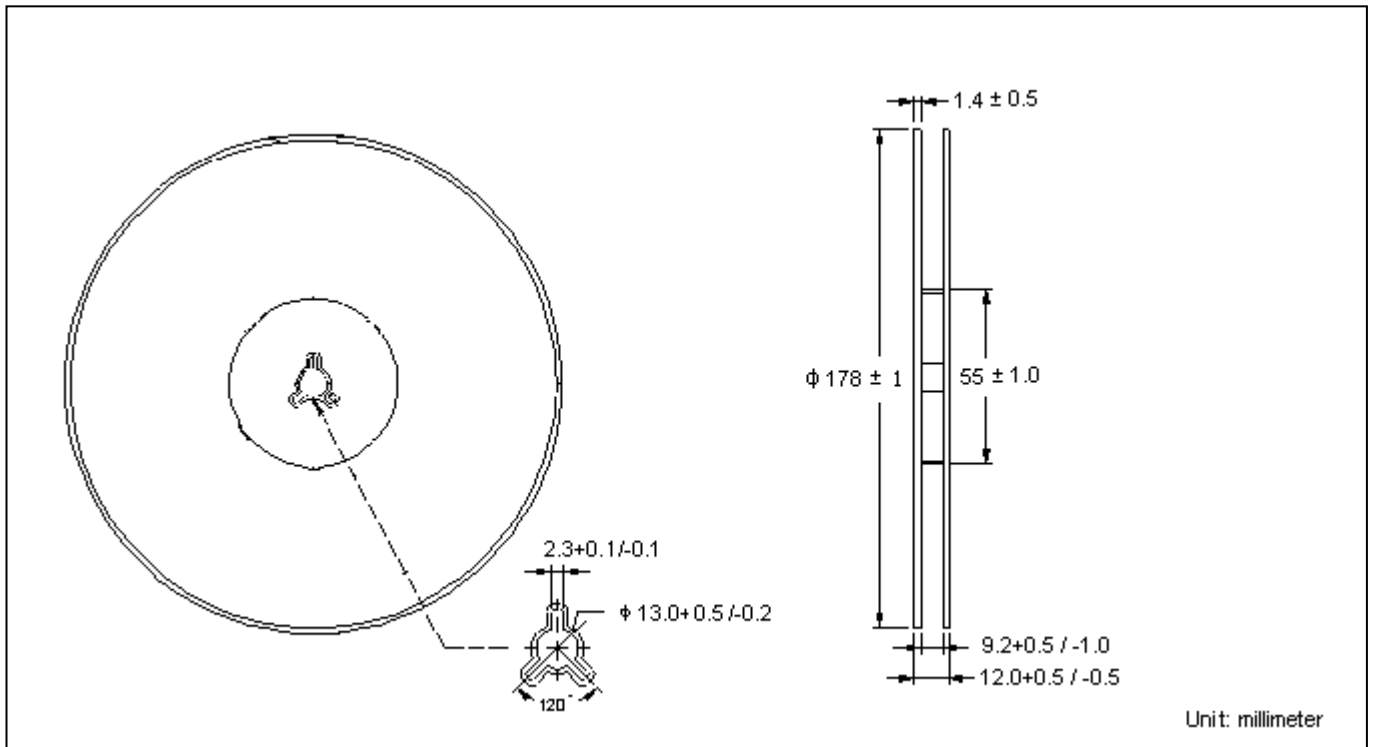
Capacitance Characteristics



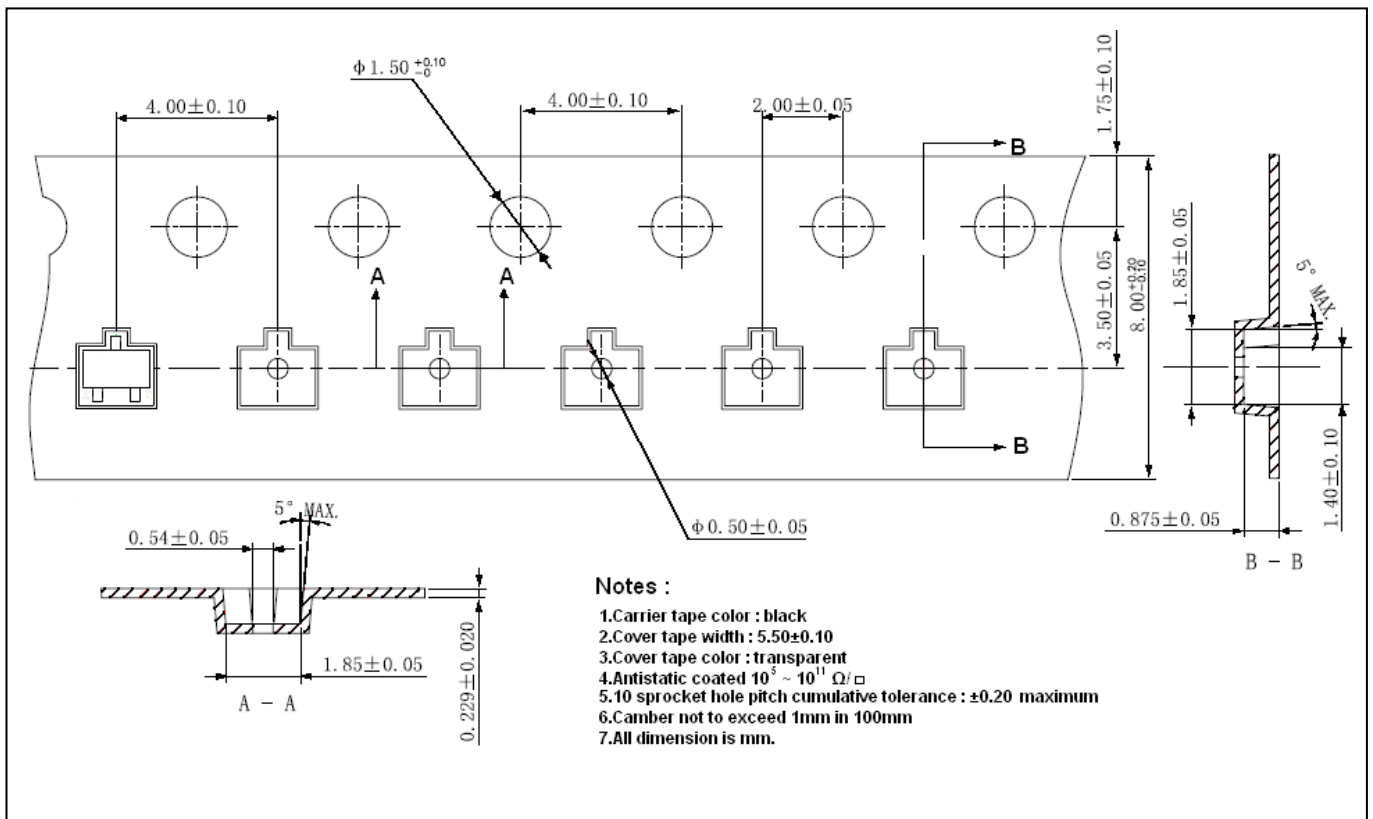
Power Derating Curve



Reel Dimension



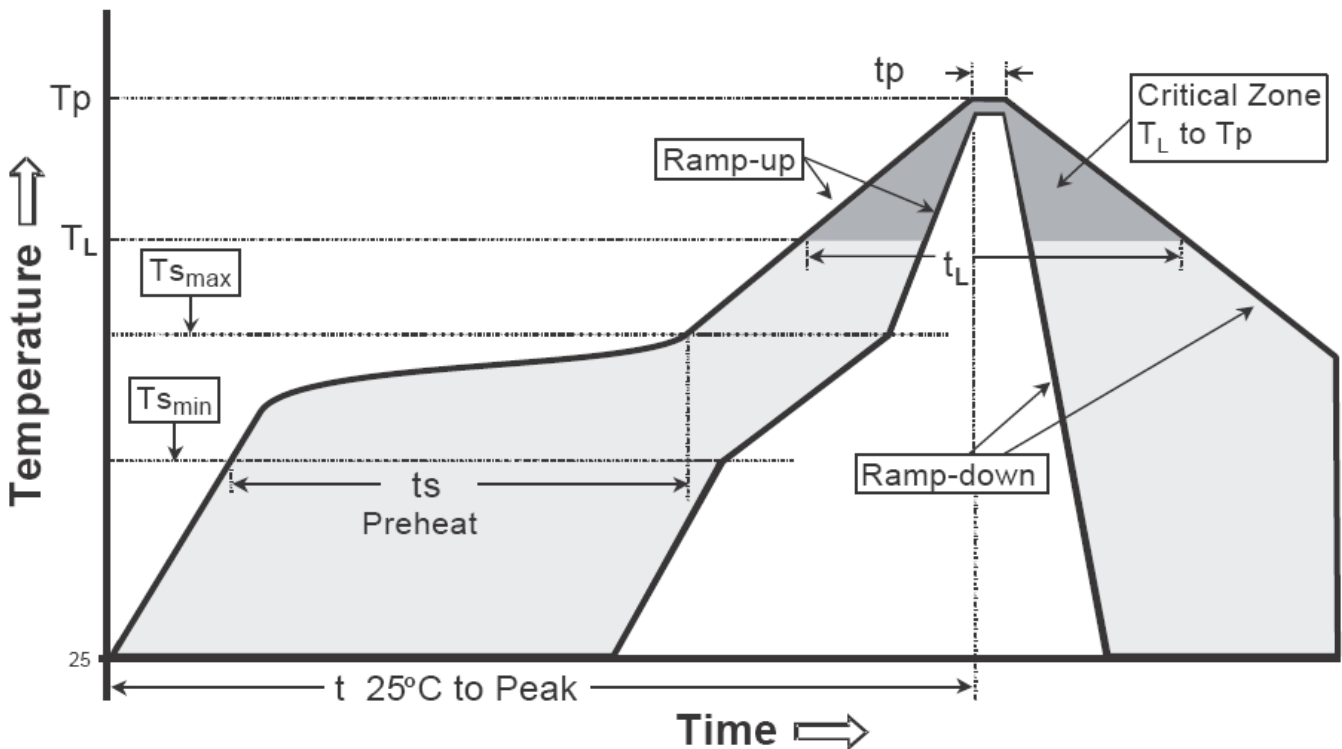
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

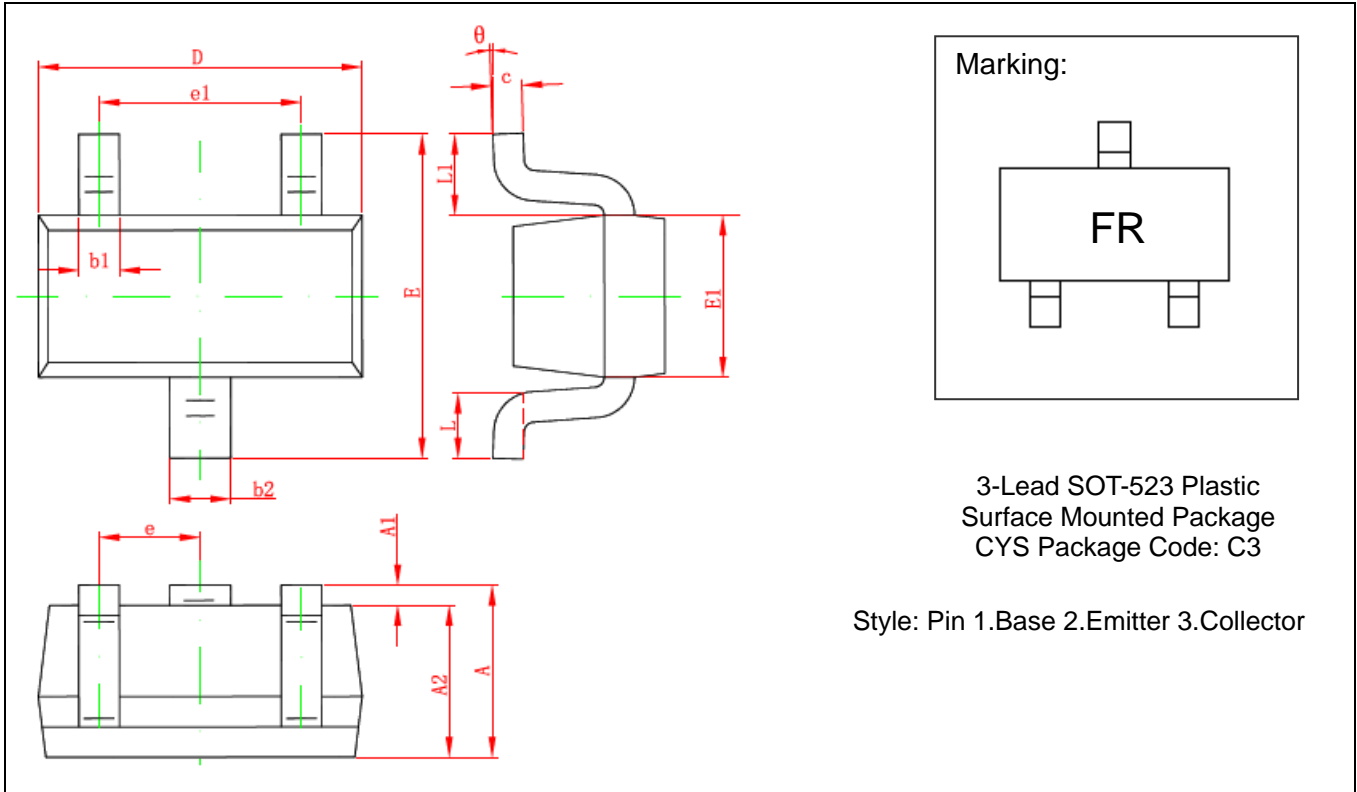
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tl)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-523 Dimension



DIM	Millimeters		Inches		DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.70	0.90	0.028	0.035	E	1.45	1.75	0.057	0.069
A1	0.00	0.10	0.000	0.004	E1	0.70	0.90	0.028	0.035
A2	0.70	0.80	0.028	0.031	e	0.50 TYP.		0.020 TYP.	
b1	0.15	0.25	0.006	0.010	e1	0.90	1.10	0.035	0.043
b2	0.25	0.35	0.010	0.014	L	0.26	0.46	0.010	0.018
c	0.10	0.20	0.004	0.008	L1	0.40 REF.		0.016 REF.	
D	1.50	1.70	0.059	0.067	θ	0°	8°	0°	8°

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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